WHAT IS CLAIMED IS:

1. A metal leadframe and associated structure for use in combination with an integrated circuit chip, comprising:
a chip mount pad having an area smaller than said chip intended for mounting; and a plurality of pad support members, each attached to the perimeter of said pad and to said leadframe; each of said support members having at least one metal portion located within the perimeter of said chip in a configuration operable to absorb thermally induced deformations of said support members.

4. The leadframe and associated structure according to Claim 1 further having a support member portion located outside the perimeter of said chip, configured in a geometry to absorb thermally induced deformations of said support members.

5. The leadframe and associated structure according to Claim 1 having a thickness in the range from about 100 to 300 μm.

6. The leadframe and associated structure according to Claim 5 comprising a metal or alloy selected from group consisting of copper, copper alloy, brass, aluminum, iron-nickel alloy, and invar.

7. The leadframe and associated structure according to Claim 1 wherein said at least one support member portion has a meandering geometry.

8. The leadframe and associated structure according to Claim 1 wherein said at least one support member portion has sinusoidal geometry.

9. The leadframe and associated structure according to Claim 1 wherein said support member can accommodate a plurality of bendings.

10. A semiconductor device comprising:
a metal leadframe and a chip mount pad; an integrated circuit chip mounted on pad, said pad having an area smaller than said chip, and a

plurality of support members, each attached externally to the perimeter of said pad and internally to said leadframe;

each of said support members having at least one metal portion located within the perimeter of said chip in a configuration operable to absorb thermally induced deformations of said support member.

13. A device as in claim 10 wherein said at least one metal portion has a meandering geometry.

14. A device as in claim 10 wherein said at least one metal potion has a sinusoidal geometry.